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Part Number: [73656-1000](#)
Status: **Active**
Overview: HDM®
Description: 2.00mm Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm

Documents:

[3D Model](#) [Application Specification AS-73656-1998 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73670-9999 \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series [73656](#)
 Application Backplane
 Comments Midplane Power Module
 Component Type Power Header
 Overview [HDM®](#)
 Product Name HDM®
 Style N/A
 UPC 800755024791

Physical

Circuits (Loaded) 3
 Circuits (maximum) 3
 Color - Resin Black
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Beryllium Copper
 Material - Plating Mating Gold
 Material - Plating Termination Gold
 Material - Resin High Temperature Thermoplastic
 Net Weight 1.605/g
 Number of Columns 1
 Number of Pairs Open Pin Field
 Number of Rows 3
 Orientation Vertical
 PC Tail Length 3.50mm
 PCB Locator No
 PCB Retention Yes
 PCB Thickness - Recommended 2.50mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 0.051µm
 Polarized to PCB Yes
 Stackable No
 Surface Mount Compatible (SMC) No

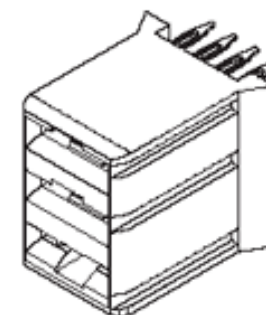


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Series

EU RoHS

**ELV and RoHS
Compliant**

REACH SVHC

**Contains SVHC: No
Low-Halogen Status
Low-Halogen**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73656Series](#)

Mates With

[73651 HDM® Board-to-Board
Daughterboard Power Module](#)

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

| Description | Product # |
|--------------------------------------|----------------------------|
| HDM Power Module | 0621001100 |
| Removal Tool | |
| Backplane Power Module Loading Heads | 0622005711 |

Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact 15A
Data Rate 1.0 Gbps
Shielded No
Voltage - Maximum 500V AC

Material Info

Reference - Drawing Numbers

Application Specification AS-73656-1998
Product Specification PS-73670-9999
Sales Drawing SDA-73656-*00*

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